



## Main Features

- On-Board Intel® Core™ processor
- 2 channel DDR4 without ECC/SO-DIMMs 2133MHz up to 32GB
- Support three independent displays with eDP and 2 x DDI (Support HDMI/DP/DVI)
- Support eMMC 5.0 up to 16G
- 5 x PCIe x1, 4 x USB 3.0, 8 x USB 2.0, 3 x SATA 3.0 and GbE
- Support Windows 10

## Product Overview

The ICES 673 is a COM Express Type 6 compact size module which features Intel® Core™ MCP processor (codename Skylake) and supports dual DDR4 SO-DIMM memory sockets with Non-ECC support, up to 32GB 2133MHz. It is integrated with Intel® integration graphics for powerful graphics processing and through interfaces like eDP and 2 x DDI. This new ICES 673 supports triple displays, on board eMMC up to 16G, and advanced I/O interfaces such as 5 x PCI Express gen. 3, 3 x SATA3.0, and 8 x USB 2.0.

## Specifications

### CPU Support

- Support Intel® Core™ i5-6300U processor

### Main Memory

- Dual 204-pin SO-DIMM sockets supports up to 32 GB DDR4 2133 MHz SDRAM

### BIOS

- AMI System BIOS
- Plug and play support
- Advanced Power Management and Advanced Configuration & Power Interface support

### Display

- Integrated Intel® Gen.8 Graphics Engine support
- Triple independent display integrated GT1/GT2/GT3 to support: eDP + 2 x DDI (Support HDMI/DP/DVI)

### COM Express Connector

- AB :
  - HDA/2 x SATA 3.0/GbE/4 x PCIe x1/8 x USB 2.0/LPC bus/GPIO/SMBus (I2C)/SPI BIOS

- CD:
  - 2 x DDI (Support HDMI/DP/DVI)
  - 4 x USB 3.0
  - 5 x PCIe x1 Gen.3

### Power Requirements

- +12VDC, +5Vsb
- Support both AT and ATX power supply mode
- One 3 pins 90 degree edge-connector for DC +12V fan

### Dimensions

- 95mm (W) x 95mm (L)

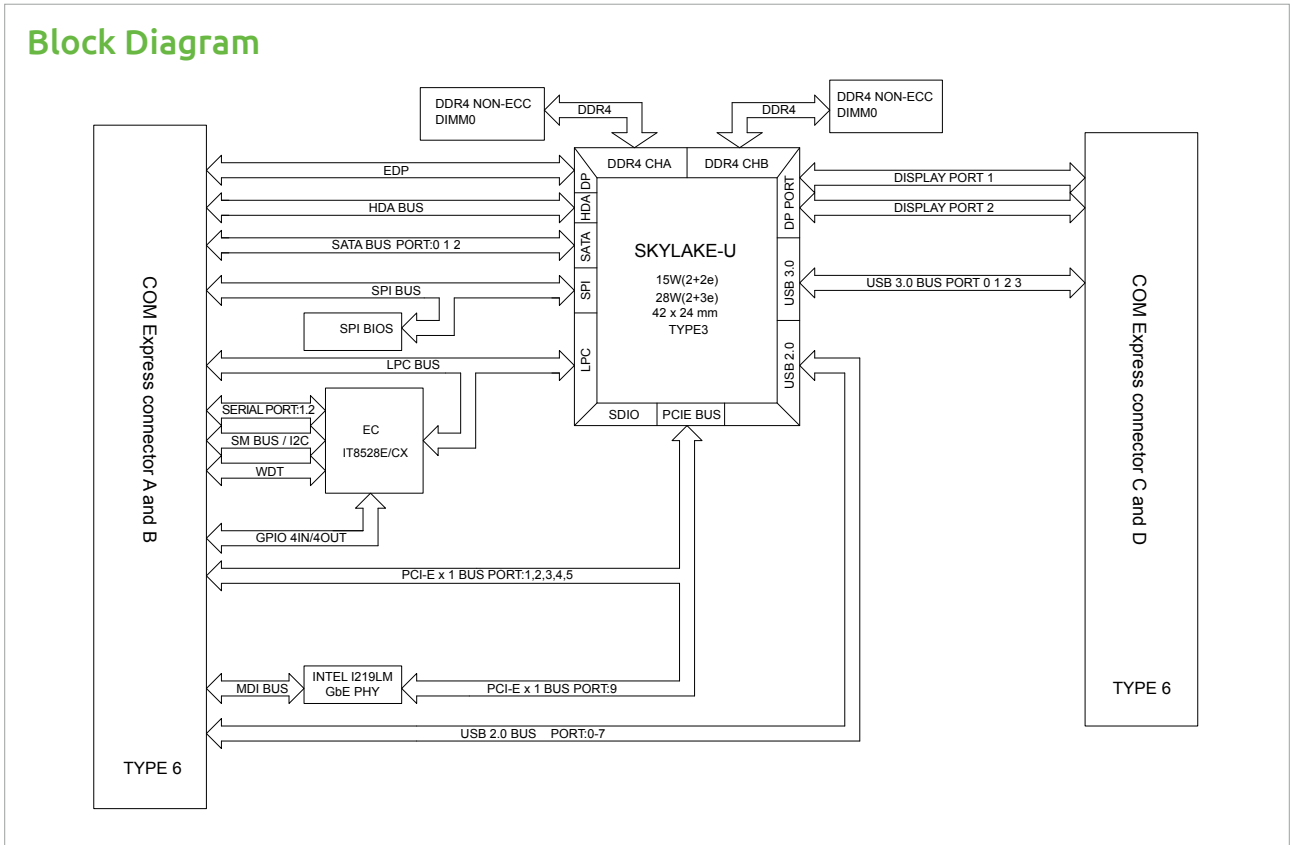
### Environment

- Board level operating temperatures: -10°C to 60°C
- Storage temperatures: -20°C to 85°C
- Relative humidity:
  - 10% to 90% (operating, non-condensing)
  - 5% to 95% (non-operating, non-condensing)

### Certifications

- Meet CE/FCC Class B

## Block Diagram



## Ordering Information

- **ICES 673 (P/N: 10K00067300X0)**

Intel® Core™ i5-6300U processor, type 6 COM Express compact module, 2 x SO-DIMMs non-ECC DDR4 (2133MHz/32GB), 5 x PCIe x1, 3 x USB 3.0, 8 x USB 2.0, 2 x SATA 3.0, 1 x GbE, 1 x eDP, 2 x DDI (HDMI 1.4/DisplayPort 1.2/DVI)